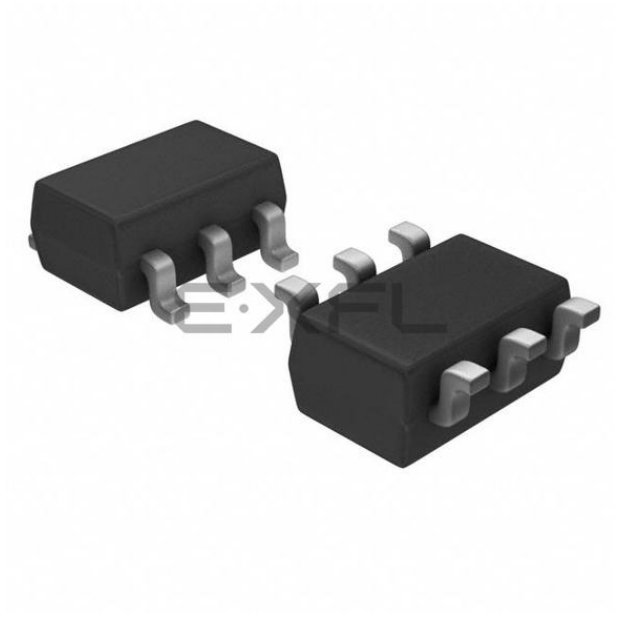

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	PIC
Core Size	8-Bit
Speed	16MHz
Connectivity	-
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	3
Program Memory Size	448B (256 x 14)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	64 x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 3x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	SOT-23-6
Supplier Device Package	SOT-23-6
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic10lf320-e-ot

2.2 Data Memory Organization

The data memory is in one bank, which contains the General Purpose Registers (GPR) and the Special Function Registers (SFR). The RP<1:0> bits of the STATUS register are the bank select bits.

RP1	RP0	
0	0	→ Bank 0 is selected

The bank extends up to 7Fh (128 bytes). The lower locations of the bank are reserved for the Special Function Registers. Above the Special Function Registers are the General Purpose Registers, implemented as Static RAM.

2.2.1 GENERAL PURPOSE REGISTER FILE

The register file is organized as 64 x 8 in the PIC10(L)F320/322. Each register is accessed, either directly or indirectly, through the File Select Register (FSR) (see **Section 2.4 “Indirect Addressing, INDF and FSR Registers”**).

2.2.2 SPECIAL FUNCTION REGISTERS

The Special Function Registers are registers used by the CPU and peripheral functions for controlling the desired operation of the device (see Table 2-3). These registers are static RAM.

The special registers can be classified into two sets: core and peripheral. The Special Function Registers associated with the “core” are described in this section. Those related to the operation of the peripheral features are described in the section of that peripheral feature.

4.4 Register Definitions: Reference Clock Control

REGISTER 4-1: CLKRCON – REFERENCE CLOCK CONTROL REGISTER

U-0	R/W-0/0	U-0	U-0	U-0	U-0	U-0	U-0
—	CLKROE	—	—	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown
q = Value depends on condition			

bit 7 **Unimplemented:** Read as '0'

bit 6 **CLKROE:** Reference Clock Output Enable bit
- 1 = Reference Clock output (CLKR), regardless of TRIS
- 0 = Reference Clock output disabled

bit 5-0 **Unimplemented:** Read as '0'

4.5 Register Definitions: Oscillator Control

REGISTER 4-2: OSCCON: OSCILLATOR CONTROL REGISTER

U-0	R/W-1/1	R/W-1/1	R/W-0/0	R-0/0	U-0	R-0/0	R-0/0
—	IRCF<2:0>			HFIOFR	—	LFIOFR	HFIOFS
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	q = Value depends on condition

bit 7 **Unimplemented:** Read as '0'

bit 6-4 **IRCF<2:0>:** INTOSC (FOSC) Frequency Select bits
- 111 = 16 MHz
- 110 = 8 MHz (default value)
- 101 = 4 MHz
- 100 = 2 MHz
- 011 = 1 MHz
- 010 = 500 kHz
- 001 = 250 kHz
- 000 = 31 kHz (LFINTOSC)

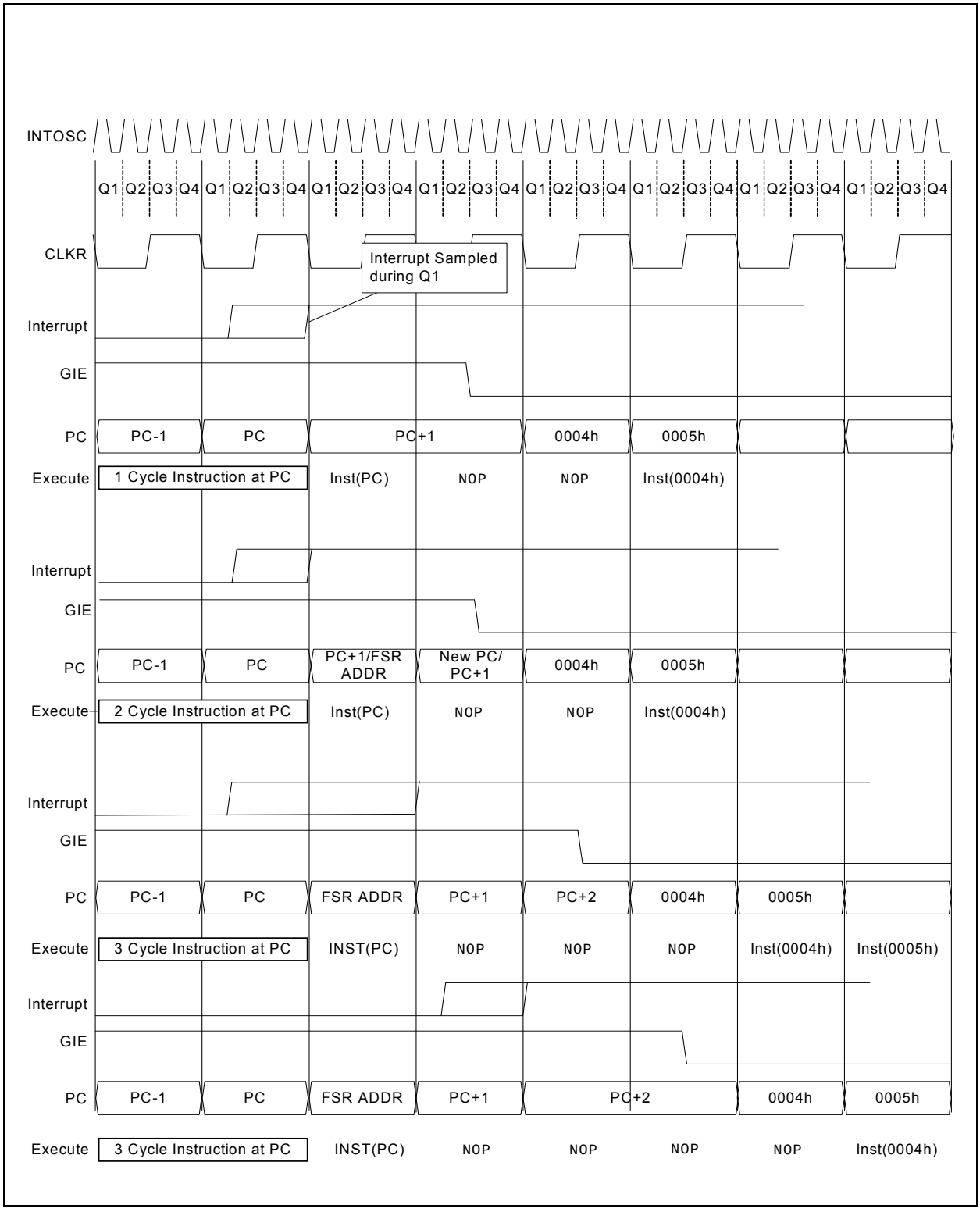
bit 3 **HFIOFR:** High-Frequency Internal Oscillator Ready bit
- 1 = 16 MHz Internal Oscillator (HFINTOSC) is ready
- 0 = 16 MHz Internal Oscillator (HFINTOSC) is not ready

bit 2 **Unimplemented:** Read as '0'

bit 1 **LFIOFR:** Low-Frequency Internal Oscillator Ready bit
- 1 = 31 kHz Internal Oscillator (LFINTOSC) is ready
- 0 = 31 kHz Internal Oscillator (LFINTOSC) is not ready

bit 0 **HFIOFS:** High-Frequency Internal Oscillator Stable bit
- 1 = 16 MHz Internal Oscillator (HFINTOSC) is stable
- 0 = 16 MHz Internal Oscillator (HFINTOSC) is not stable

FIGURE 6-2: INTERRUPT LATENCY



6.3 Interrupts During Sleep

Some interrupts can be used to wake from Sleep. To wake from Sleep, the peripheral must be able to operate without the system clock. The interrupt source must have the appropriate Interrupt Enable bit(s) set prior to entering Sleep.

On waking from Sleep, if the GIE bit is also set, the processor will branch to the interrupt vector. Otherwise, the processor will continue executing instructions after the SLEEP instruction. The instruction directly after the SLEEP instruction will always be executed before branching to the ISR. Refer to the **Section 7.0 "Power-Down Mode (Sleep)"** for more details.

6.4 INT Pin

The INT pin can be used to generate an asynchronous edge-triggered interrupt. This interrupt is enabled by setting the INTE bit of the INTCON register. The INTEDG bit of the OPTION_REG register determines on which edge the interrupt will occur. When the INTEDG bit is set, the rising edge will cause the interrupt. When the INTEDG bit is clear, the falling edge will cause the interrupt. The INTF bit of the INTCON register will be set when a valid edge appears on the INT pin. If the GIE and INTE bits are also set, the processor will redirect program execution to the interrupt vector.

6.5 Context Saving During Interrupts

During an interrupt, only the return PC value is saved on the stack. Typically, users may wish to save key registers during an interrupt (e.g., W and STATUS registers). This must be implemented in software.

Temporary holding registers W_TEMP and STATUS_TEMP should be placed in the last 16 bytes of GPR (see Table 1-2). This makes context save and restore operations simpler. The code shown in Example 6-1 can be used to:

- Store the W register
- Store the STATUS register
- Execute the ISR code
- Restore the Status (and Bank Select Bit register)
- Restore the W register

Note:	These devices do not require saving the PCLATH. However, if computed GOTOs are used in both the ISR and the main code, the PCLATH must be saved and restored in the ISR.

EXAMPLE 6-1: SAVING STATUS AND W REGISTERS IN RAM

```
MOVWF   W_TEMP              ;Copy W to TEMP register
SWAPF   STATUS,W            ;Swap status to be saved into W
                            ;Swaps are used because they do not affect the status bits
MOVWF   STATUS_TEMP         ;Save status to bank zero STATUS_TEMP register
:
:(ISR)                      ;Insert user code here
:
SWAPF   STATUS_TEMP,W       ;Swap STATUS_TEMP register into W
                            ;(sets bank to original state)
MOVWF   STATUS              ;Move W into STATUS register
SWAPF   W_TEMP,F            ;Swap W_TEMP
SWAPF   W_TEMP,W            ;Swap W_TEMP into W
```

8.1 Independent Clock Source

The WDT derives its time base from the 31 kHz LFINTOSC internal oscillator. Time intervals in this chapter are based on a nominal interval of 1ms. See **Section 24.0 "Electrical Specifications"** for the LFINTOSC tolerances.

8.2 WDT Operating Modes

The Watchdog Timer module has four operating modes controlled by the WDTE<1:0> bits in Configuration Word. See Table 8-1.

8.2.1 WDT IS ALWAYS ON

When the WDTE bits of Configuration Word are set to '11', the WDT is always on.

WDT protection is active during Sleep.

8.2.2 WDT IS OFF IN SLEEP

When the WDTE bits of Configuration Word are set to '10', the WDT is on, except in Sleep.

WDT protection is not active during Sleep.

8.2.3 WDT CONTROLLED BY SOFTWARE

When the WDTE bits of Configuration Word are set to '01', the WDT is controlled by the SWDTEN bit of the WDTCON register.

WDT protection is unchanged by Sleep. See Table 8-1 for more details.

TABLE 8-1: WDT OPERATING MODES

WDTE<1:0>	SWDTEN	Device Mode	WDT Mode
11	X	X	Active
10	X	Awake	Active
		Sleep	Disabled
01	1	X	Active
	0		Disabled
00	X	X	Disabled

8.3 Time-Out Period

The WDTPS bits of the WDTCON register set the time-out period from 1 ms to 256 seconds (nominal). After a Reset, the default time-out period is 2 seconds.

8.4 Clearing the WDT

The WDT is cleared when any of the following conditions occur:

- Any Reset
- CLRWDT instruction is executed
- Device enters Sleep
- Device wakes up from Sleep
- Oscillator fail
- WDT is disabled

See Table 8-2 for more information.

8.5 Operation During Sleep

When the device enters Sleep, the WDT is cleared. If the WDT is enabled during Sleep, the WDT resumes counting.

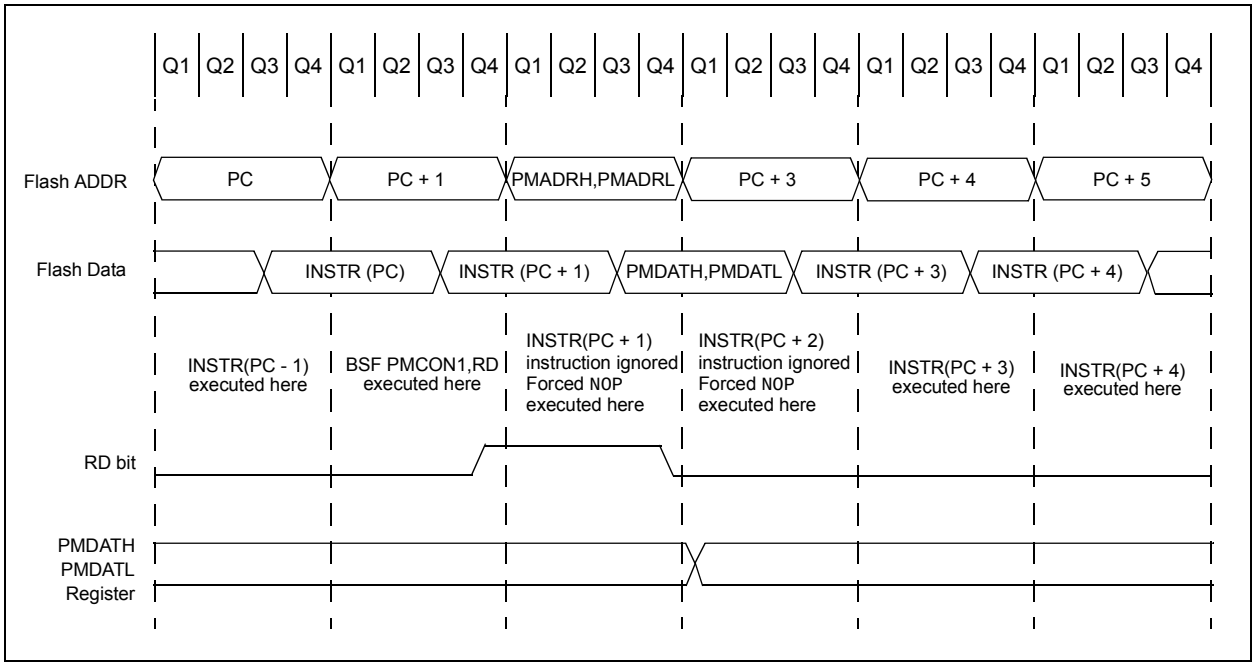
When the device exits Sleep, the WDT is cleared again.

When a WDT time-out occurs while the device is in Sleep, no Reset is generated. Instead, the device wakes up and resumes operation. The $\overline{TO}$ and $\overline{PD}$ bits in the STATUS register are changed to indicate the event. See **Section 2.0 "Memory Organization"** and ***Register 2-1*** for more information.

TABLE 8-2: WDT CLEARING CONDITIONS

Conditions	WDT
WDTE<1:0> = 00	Cleared
WDTE<1:0> = 01 and SWDTEN = 0	
WDTE<1:0> = 10 and enter Sleep	
CLRWDT Command	
Exit Sleep	
Change INTOSC divider (IRCF bits)	Unaffected

FIGURE 9-2: FLASH PROGRAM MEMORY READ CYCLE EXECUTION



EXAMPLE 9-1: FLASH PROGRAM MEMORY READ

```
* This code block will read 1 word of program
* memory at the memory address:
    PROG_ADDR_HI: PROG_ADDR_LO
*   data will be returned in the variables;
*   PROG_DATA_HI, PROG_DATA_LO

    BANKSEL  PMADRL           ; not required on devices with 1 Bank of SFRs
    MOVLW    PROG_ADDR_LO     ;
    MOVWF    PMADRL           ; Store LSB of address
    MOVLW    PROG_ADDR_HI     ;
    MOVWF    PMADRH           ; Store MSB of address

    BCF      PMCON1,CFGS      ; Do not select Configuration Space
    BSF      PMCON1,RD        ; Initiate read
    NOP                       ; Ignored (Figure 9-2)
    NOP                       ; Ignored (Figure 9-2)

    MOVF     PMDATL,W         ; Get LSB of word
    MOVWF    PROG_DATA_LO     ; Store in user location
    MOVF     PMDATH,W         ; Get MSB of word
    MOVWF    PROG_DATA_HI     ; Store in user location
```

9.2.4 WRITING TO FLASH PROGRAM MEMORY

Program memory is programmed using the following steps:

1. Load the address in PMADRH:PMADRL of the row to be programmed.
2. Load each write latch with data.
3. Initiate a programming operation.
4. Repeat steps 1 through 3 until all data is written.

Before writing to program memory, the word(s) to be written must be erased or previously unwritten. Program memory can only be erased one row at a time. No automatic erase occurs upon the initiation of the write.

Program memory can be written one or more words at a time. The maximum number of words written at one time is equal to the number of write latches. See Figure 9-5 (row writes to program memory with 16 write latches) for more details.

The write latches are aligned to the Flash row address boundary defined by the upper ten bits of PMADRH:PMADRL, (PMADRH<6:0>:PMADRL<7:5>) with the lower five bits of PMADRL, (PMADRL<4:0>) determining the write latch being loaded. Write operations do not cross these boundaries. At the completion of a program memory write operation, the data in the write latches is reset to contain 0x3FFF.

The following steps should be completed to load the write latches and program a row of program memory. These steps are divided into two parts. First, each write latch is loaded with data from the PMDATH:PMDATL using the unlock sequence with LWLO = 1. When the last word to be loaded into the write latch is ready, the LWLO bit is cleared and the unlock sequence executed. This initiates the programming operation, writing all the latches into Flash program memory.

Note:	The special unlock sequence is required to load a write latch with data or initiate a Flash programming operation. If the unlock sequence is interrupted, writing to the latches or program memory will not be initiated.

1. Set the WREN bit of the PMCON1 register.
2. Clear the CFGS bit of the PMCON1 register.
3. Set the LWLO bit of the PMCON1 register. When the LWLO bit of the PMCON1 register is '1', the write sequence will only load the write latches and will not initiate the write to Flash program memory.
4. Load the PMADRH:PMADRL register pair with the address of the location to be written.
5. Load the PMDATH:PMDATL register pair with the program memory data to be written.
6. Execute the unlock sequence (**Section 9.2.2 "Flash Memory Unlock Sequence"**). The write latch is now loaded.
7. Increment the PMADRH:PMADRL register pair to point to the next location.
8. Repeat steps 5 through 7 until all but the last write latch has been loaded.
9. Clear the LWLO bit of the PMCON1 register. When the LWLO bit of the PMCON1 register is '0', the write sequence will initiate the write to Flash program memory.
10. Load the PMDATH:PMDATL register pair with the program memory data to be written.
11. Execute the unlock sequence (**Section 9.2.2 "Flash Memory Unlock Sequence"**). The entire program memory latch content is now written to Flash program memory.

Note:	The program memory write latches are reset to the blank state (0x3FFF) at the completion of every write or erase operation. As a result, it is not necessary to load all the program memory write latches. Unloaded latches will remain in the blank state.

An example of the complete write sequence is shown in Example 9-3. The initial address is loaded into the PMADRH:PMADRL register pair; the data is loaded using indirect addressing.

REGISTER 10-3: LATA: PORTA DATA LATCH REGISTER

U-0	U-0	U-0	U-0	U-0	R/W-x/u	R/W-x/u	R/W-x/u
—	—	—	—	—	LATA2	LATA1	LATA0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-3 **Unimplemented**: Read as ‘0’.

bit 2-0 **LATA<2:0>:** RA<2:0> Output Latch Value bits

Note 1: Writes to PORTx are actually written to the corresponding LATx register. Reads from LATx register return register values, not I/O pin values.

REGISTER 10-4: ANSELA: PORTA ANALOG SELECT REGISTER

U-0	U-0	U-0	U-0	U-0	R/W-1/1	R/W-1/1	R/W-1/1
—	—	—	—	—	ANSA2	ANSA1	ANSA0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-3 **Unimplemented:** Read as ‘0’.

bit 2-0 **ANSA<2:0>**: Analog Select between Analog or Digital Function on Pins RA<2:0>, respectively

1 = Analog input. Pin is assigned as analog input(1). Digital Input buffer disabled.

0 = Digital I/O. Pin is assigned to port or Digital special function.

Note 1: Setting a pin to an analog input automatically disables the digital input circuitry. Weak pull-ups, if available, are unaffected. The corresponding TRIS bit must be set to Input mode by the user in order to allow external control of the voltage on the pin.

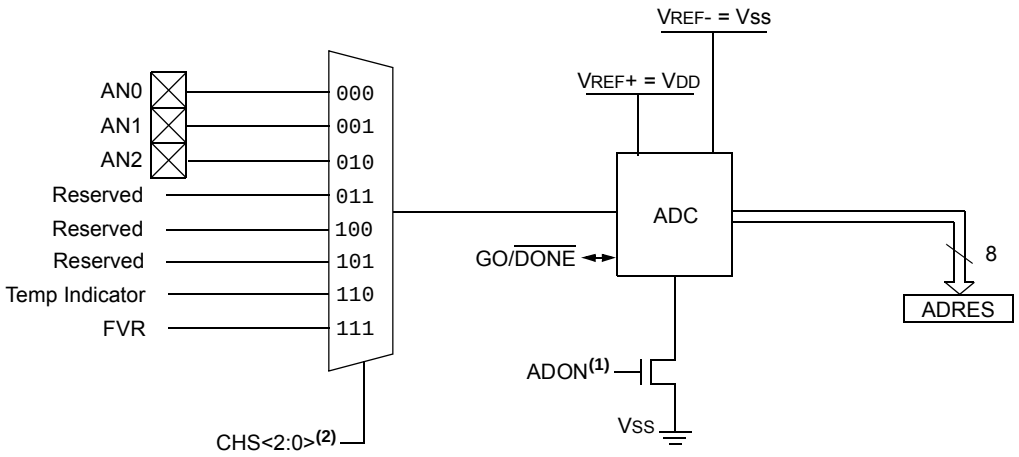
15.0 ANALOG-TO-DIGITAL CONVERTER (ADC) MODULE

The Analog-to-Digital Converter (ADC) converts an analog input signal to an 8-bit binary representation of that signal. This device uses three analog input channels, which are multiplexed into a single sample and hold circuit. The output of the sample and hold is connected to the input of the converter. The converter generates an 8-bit binary result via successive approximation and stores the conversion result into the ADC result register (ADRES). Figure 15-1 shows the block diagram of the ADC.

The ADC voltage reference is software selectable to be internally generated.

The ADC can generate an interrupt upon completion of a conversion. This interrupt can be used to wake-up the device from Sleep.

FIGURE 15-1: ADC SIMPLIFIED BLOCK DIAGRAM



Note 1: When ADON = 0, all multiplexer inputs are disconnected.

2: See ADCON register (Register 15-1) for detailed analog channel selection per device.

15.2.5 A/D CONVERSION PROCEDURE

This is an example procedure for using the ADC to perform an Analog-to-Digital conversion:

1. Configure Port:
   - Disable pin output driver (Refer to the TRIS register)
   - Configure pin as analog (Refer to the ANSEL register)
   - Disable weak pull-ups either globally (Refer to the OPTION_REG register) or individually (Refer to the appropriate WPUX register)
2. Configure the ADC module:
   - Select ADC conversion clock
   - Select ADC input channel
   - Turn on ADC module
3. Configure ADC interrupt (optional):
   - Clear ADC interrupt flag
   - Enable ADC interrupt
   - Enable peripheral interrupt
   - Enable global interrupt**(1)**
4. Wait the required acquisition time**(2)**.
5. Start conversion by setting the GO/$\overline{\text{DONE}}$ bit.
6. Wait for ADC conversion to complete by one of the following:
   - Polling the GO/$\overline{\text{DONE}}$ bit
   - Waiting for the ADC interrupt (interrupts enabled)
7. Read ADC Result.
8. Clear the ADC interrupt flag (required if interrupt is enabled).

Note 1: The global interrupt can be disabled if the user is attempting to wake-up from Sleep and resume in-line code execution.

2: Refer to **Section 15.4 "A/D Acquisition Requirements"**.

15.4 A/D Acquisition Requirements

For the ADC to meet its specified accuracy, the charge holding capacitor (CHOLD) must be allowed to fully charge to the input channel voltage level. The Analog Input model is shown in Figure 15-3. The source impedance (RS) and the internal sampling switch (RSS) impedance directly affect the time required to charge the capacitor CHOLD. The sampling switch (RSS) impedance varies over the device voltage (VDD), refer to Figure 15-3. **The maximum recommended impedance for analog sources is 10 kΩ.** As the source impedance is decreased, the acquisition time may be decreased. After the analog input channel is selected (or changed), an A/D acquisition must be done before the conversion can be started. To calculate the minimum acquisition time, Equation 15-1 may be used. This equation assumes that 1/2 LSb error is used (511 steps for the ADC). The 1/2 LSb error is the maximum error allowed for the ADC to meet its specified resolution.

EQUATION 15-1: ACQUISITION TIME EXAMPLE

Assumptions: $Temperature = 50°C$ *and external impedance of* $10k\Omega$ *5.0V* V_{DD}

$$T_{ACQ} = \text{Amplifier Settling Time} + \text{Hold Capacitor Charging Time} + \text{Temperature Coefficient}$$
$$= T_{AMP} + T_C + T_{COFF}$$
$$= 2\mu s + T_C + [(Temperature - 25°C)(0.05\mu s/°C)]$$

The value for T_C *can be approximated with the following equations:*

$$V_{APPLIED}\left(1 - \frac{1}{(2^{n+1}) - 1}\right) = V_{CHOLD}$$;[1] V_{CHOLD} *charged to within 1/2 lsb*

$$V_{APPLIED}\left(1 - e^{\frac{-T_C}{RC}}\right) = V_{CHOLD}$$;[2] V_{CHOLD} *charge response to* $V_{APPLIED}$

$$V_{APPLIED}\left(1 - e^{\frac{-T_C}{RC}}\right) = V_{APPLIED}\left(1 - \frac{1}{(2^{n+1}) - 1}\right)$$;combining [1] and [2]

Note: Where n = number of bits of the ADC.

Solving for T_C*:*

$$T_C = -C_{HOLD}(R_{IC} + R_{SS} + R_S)\ ln(1/511)$$
$$= -10pF(1k\Omega + 7k\Omega + 10k\Omega)\ ln(0.001957)$$
$$= 1.12\mu s$$

Therefore:

$$T_{ACQ} = 2\mu s + 1.12\mu s + [(50°C - 25°C)(0.05\mu s/°C)]$$
$$= 4.37\mu s$$

Note 1: The reference voltage (VREF) has no effect on the equation, since it cancels itself out.

2: The charge holding capacitor (CHOLD) is not discharged after each conversion.

3: The maximum recommended impedance for analog sources is 10 kΩ. This is required to meet the pin leakage specification.

18.1 PWMx Pin Configuration

All PWM outputs are multiplexed with the PORT data latch. The user must configure the pins as outputs by clearing the associated TRIS bits.

Note:	Clearing the PWMxOE bit will relinquish control of the PWMx pin.

18.1.1 FUNDAMENTAL OPERATION

The PWM module produces a 10-bit resolution output. Timer2 and PR2 set the period of the PWM. The PWMxDCL and PWMxDCH registers configure the duty cycle. The period is common to all PWM modules, whereas the duty cycle is independently controlled.

Note:	The Timer2 postscaler is not used in the determination of the PWM frequency. The postscaler could be used to have a servo update rate at a different frequency than the PWM output.

All PWM outputs associated with Timer2 are set when TMR2 is cleared. Each PWMx is cleared when TMR2 is equal to the value specified in the corresponding PWMxDCH (8 MSb) and PWMxDCL<7:6> (2 LSb) registers. When the value is greater than or equal to PR2, the PWM output is never cleared (100% duty cycle).

Note:	The PWMxDCH and PWMxDCL registers are double buffered. The buffers are updated when Timer2 matches PR2. Care should be taken to update both registers before the timer match occurs.

18.1.2 PWM OUTPUT POLARITY

The output polarity is inverted by setting the PWMxPOL bit of the PWMxCON register.

18.1.3 PWM PERIOD

The PWM period is specified by the PR2 register of Timer2. The PWM period can be calculated using the formula of Equation 18-1.

EQUATION 18-1: PWM PERIOD

$$PWM\ Period = [(PR2) + 1] \bullet 4 \bullet T_{OSC} \bullet (TMR2\ Prescale\ Value)$$

Note: TOSC = 1/FOSC

When TMR2 is equal to PR2, the following three events occur on the next increment cycle:

- TMR2 is cleared
- The PWM output is active. (Exception: When the PWM duty cycle = 0%, the PWM output will remain inactive.)
- The PWMxDCH and PWMxDCL register values are latched into the buffers.

Note:	The Timer2 postscaler has no effect on the PWM operation.

18.1.4 PWM DUTY CYCLE

The PWM duty cycle is specified by writing a 10-bit value to the PWMxDCH and PWMxDCL register pair. The PWMxDCH register contains the eight MSbs and the PWMxDCL<7:6>, the two LSbs. The PWMxDCH and PWMxDCL registers can be written to at any time.

Equation 18-2 is used to calculate the PWM pulse width.

Equation 18-3 is used to calculate the PWM duty cycle ratio.

EQUATION 18-2: PULSE WIDTH

$$Pulse\ Width = (PWMxDCH:PWMxDCL<7:6>) \bullet T_{OSC} \bullet (TMR2\ Prescale\ Value)$$

Note: TOSC = 1/FOSC

EQUATION 18-3: DUTY CYCLE RATIO

$$Duty\ Cycle\ Ratio = \frac{(PWMxDCH:PWMxDCL<7:6>)}{4(PR2 + 1)}$$

The 8-bit timer TMR2 register is concatenated with the two Least Significant bits of 1/FOSC, adjusted by the Timer2 prescaler to create the 10-bit time base. The system clock is used if the Timer2 prescaler is set to 1:1.

18.1.9 SETUP FOR PWM OPERATION USING PWMx PINS

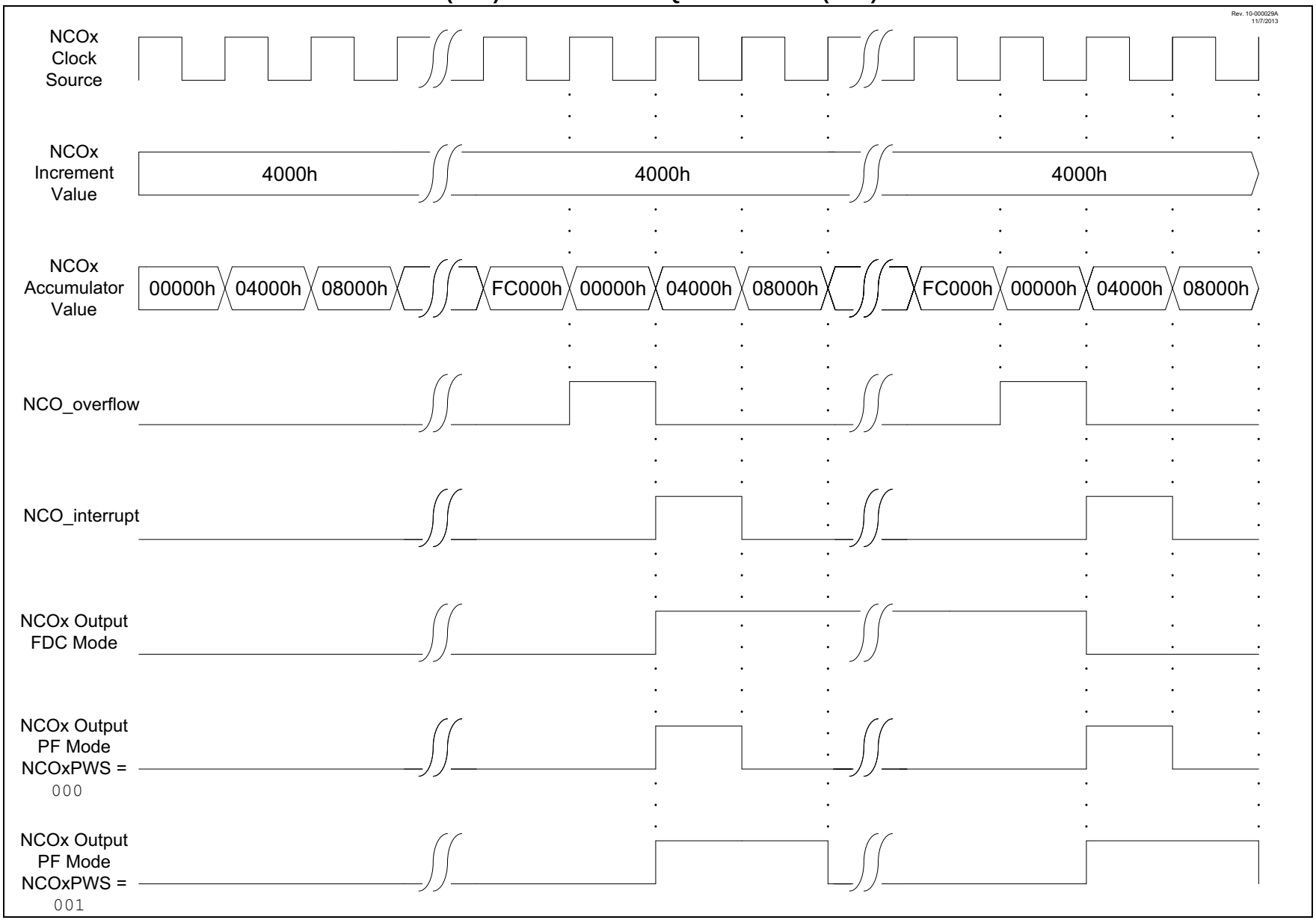
The following steps should be taken when configuring the module for PWM operation using the PWMx pins:

1. Disable the PWMx pin output driver(s) by setting the associated TRIS bit(s).
2. Clear the PWMxCON register.
3. Load the PR2 register with the PWM period value.
4. Clear the PWMxDCH register and bits <7:6> of the PWMxDCL register.
5. Configure and start Timer2:
   - Clear the TMR2IF interrupt flag bit of the PIR1 register. See Note below.
   - Configure the T2CKPS bits of the T2CON register with the Timer2 prescale value.
   - Enable Timer2 by setting the TMR2ON bit of the T2CON register.
6. Enable PWM output pin and wait until Timer2 overflows, TMR2IF bit of the PIR1 register is set. See Note below.
7. Enable the PWMx pin output driver(s) by clearing the associated TRIS bit(s) and setting the PWMxOE bit of the PWMxCON register.
8. Configure the PWM module by loading the PWMxCON register with the appropriate values.

Note 1: In order to send a complete duty cycle and period on the first PWM output, the above steps must be followed in the order given. If it is not critical to start with a complete PWM signal, then move Step 8 to replace Step 4.

2: For operation with other peripherals only, disable PWMx pin outputs.

FIGURE 20-2: NCO – FIXED DUTY CYCLE (FDC) AND PULSE FREQUENCY MODE (PFM) OUTPUT OPERATION DIAGRAM



EQUATION 21-1: DEAD-BAND DELAY TIME UNCERTAINTY

$$T_{DEADBAND\_UNCERTAINTY} = \frac{1}{Fcwg\_clock}$$

EXAMPLE 21-1: DEAD-BAND DELAY TIME UNCERTAINTY

$$Fcwg\_clock = 16\ MHz$$

Therefore:

$$T_{DEADBAND\_UNCERTAINTY} = \frac{1}{Fcwg\_clock}$$

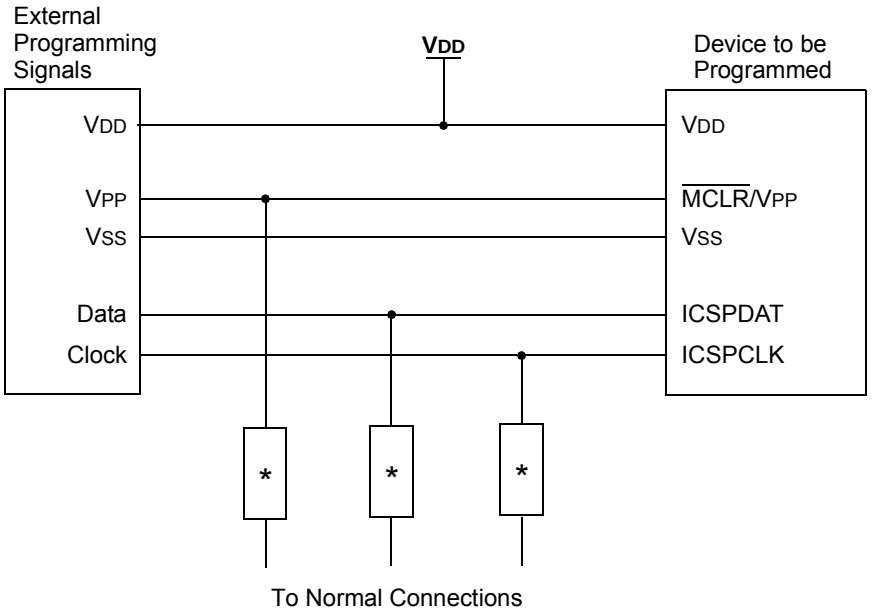
$$= \frac{1}{16\ MHz}$$

$$= 625ns$$

For additional interface recommendations, refer to your specific device programmer manual prior to PCB design.

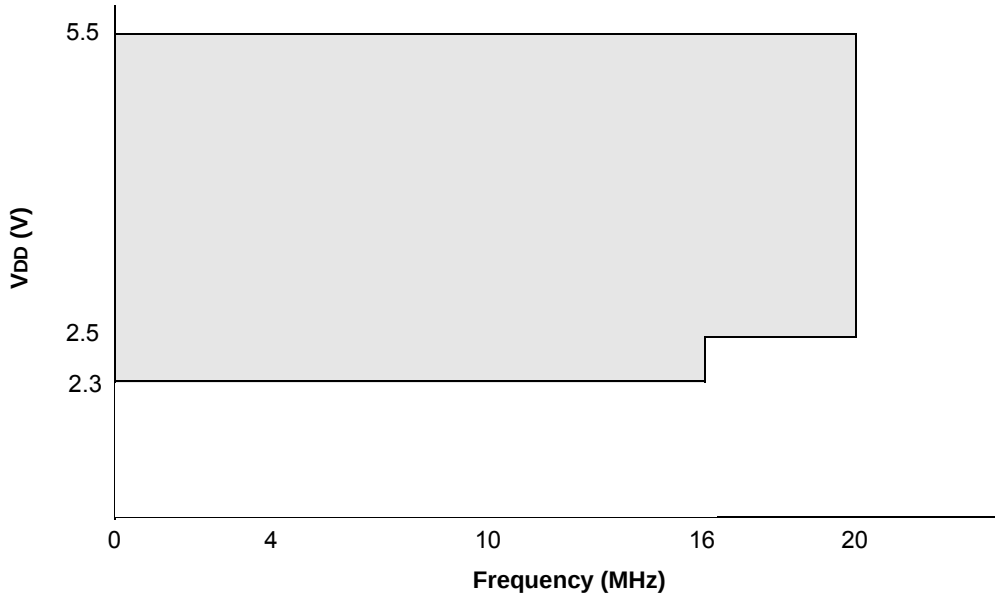
It is recommended that isolation devices be used to separate the programming pins from other circuitry. The type of isolation is highly dependent on the specific application and may include devices such as resistors, diodes, or even jumpers. See Figure 22-3 for more information.

FIGURE 22-3: TYPICAL CONNECTION FOR ICSP™ PROGRAMMING



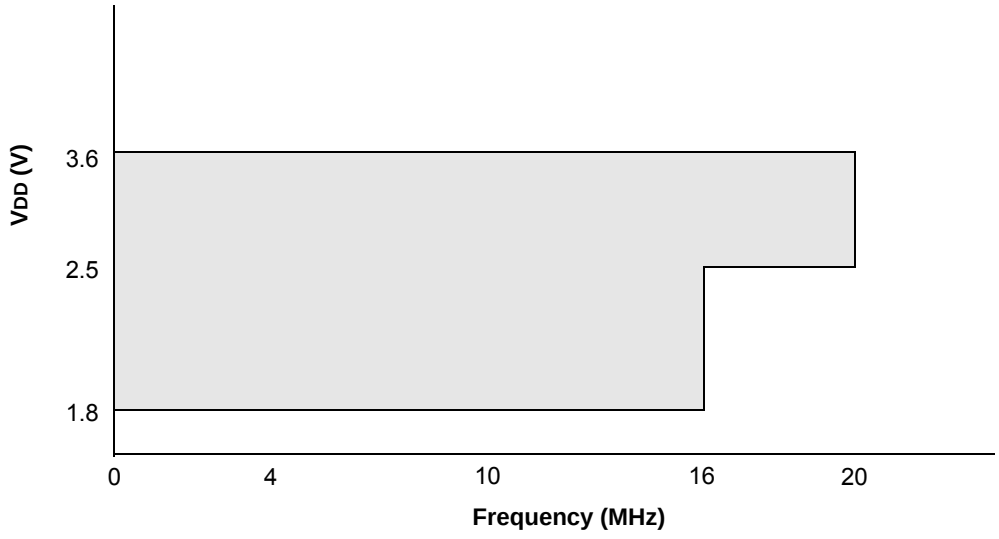
* Isolation devices (as required).

FIGURE 24-1: PIC10F320/322 VOLTAGE FREQUENCY GRAPH, -40°C ≤ TA ≤ +125°C



Note 1: The shaded region indicates the permissible combinations of voltage and frequency.
2: Refer to Table 24-6 for each Oscillator mode's supported frequencies.

FIGURE 24-2: PIC10LF320/322 VOLTAGE FREQUENCY GRAPH, -40°C ≤ TA ≤ +125°C



Note 1: The shaded region indicates the permissible combinations of voltage and frequency.
2: Refer to Table 24-6 for each Oscillator mode's supported frequencies.

TABLE 24-2: SUPPLY VOLTAGE (I_{DD})(1,2) (CONTINUED)

PIC10LF320/322			Standard Operating Conditions (unless otherwise stated)				
PIC10F320/322							
Param No.	Device Characteristics	Min.	Typ†	Max.	Units	Conditions	
						V_{DD}	Note
D017		—	213	290	μA	1.8	F_{OSC} = 500 kHz HFINTOSC mode
		—	264	360	μA	3.0	
D017		—	272	368	μA	2.3	F_{OSC} = 500 kHz HFINTOSC mode
		—	310	422	μA	3.0	
		—	372	515	μA	5.0	
D018		—	0.33	0.50	mA	1.8	F_{OSC} = 8 MHz HFINTOSC mode
		—	0.43	0.70	mA	3.0	
D018		—	0.45	1.0	mA	2.3	F_{OSC} = 8 MHz HFINTOSC mode
		—	0.56	1.1	mA	3.0	
		—	0.64	1.2	mA	5.0	
D019		—	0.46	1.1	mA	1.8	F_{OSC} = 16 MHz HFINTOSC mode
		—	0.73	1.2	mA	3.0	
D019		—	0.60	1.1	mA	2.3	F_{OSC} = 16 MHz HFINTOSC mode
		—	0.76	1.2	mA	3.0	
		—	0.85	1.3	mA	5.0	

Note 1: The test conditions for all I_{DD} measurements in active operation mode are: CLKIN = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to V_{DD}; $\overline{MCLR}$ = V_{DD}; WDT disabled.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors, such as I/O pin loading and switching rate, oscillator type, internal code execution pattern and temperature, also have an impact on the current consumption.

26.11 Demonstration/Development Boards, Evaluation Kits, and Starter Kits

A wide variety of demonstration, development and evaluation boards for various PIC MCUs and dsPIC DSCs allows quick application development on fully functional systems. Most boards include prototyping areas for adding custom circuitry and provide application firmware and source code for examination and modification.

The boards support a variety of features, including LEDs, temperature sensors, switches, speakers, RS-232 interfaces, LCD displays, potentiometers and additional EEPROM memory.

The demonstration and development boards can be used in teaching environments, for prototyping custom circuits and for learning about various microcontroller applications.

In addition to the PICDEM™ and dsPICDEM™ demonstration/development board series of circuits, Microchip has a line of evaluation kits and demonstration software for analog filter design, KEELOQ® security ICs, CAN, IrDA®, PowerSmart battery management, SEEVAL® evaluation system, Sigma-Delta ADC, flow rate sensing, plus many more.

Also available are starter kits that contain everything needed to experience the specified device. This usually includes a single application and debug capability, all on one board.

Check the Microchip web page (www.microchip.com) for the complete list of demonstration, development and evaluation kits.

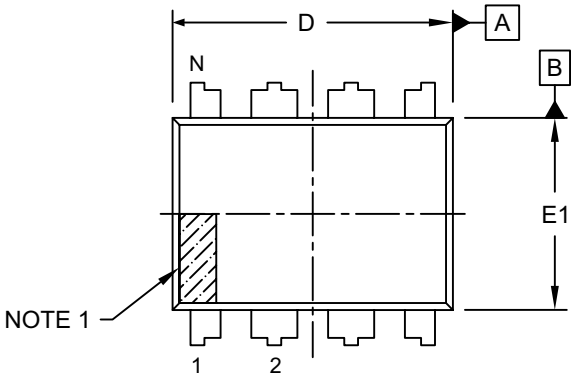
26.12 Third-Party Development Tools

Microchip also offers a great collection of tools from third-party vendors. These tools are carefully selected to offer good value and unique functionality.

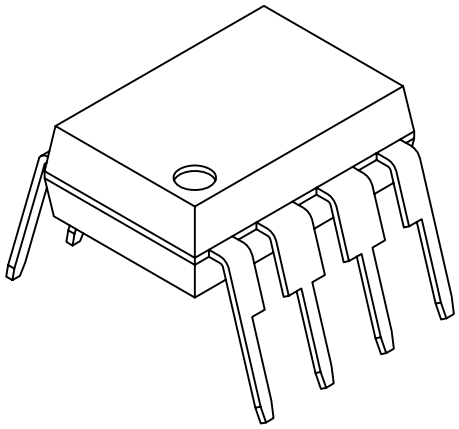
- Device Programmers and Gang Programmers from companies, such as SoftLog and CCS
- Software Tools from companies, such as Gimpel and Trace Systems
- Protocol Analyzers from companies, such as Saleae and Total Phase
- Demonstration Boards from companies, such as MikroElektronika, Digilent® and Olimex
- Embedded Ethernet Solutions from companies, such as EZ Web Lynx, WIZnet and IPLogika®

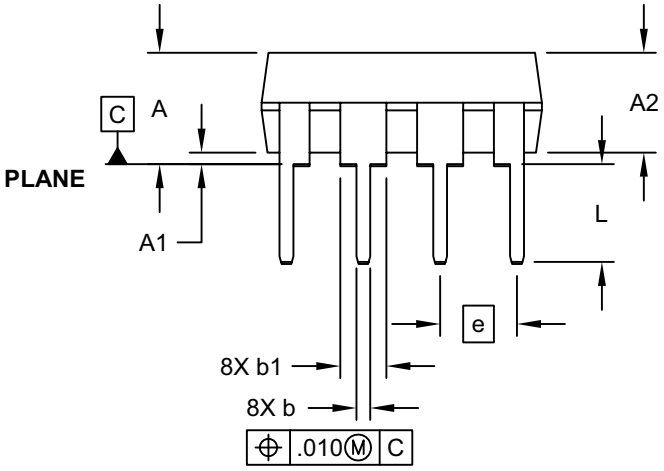
8-Lead Plastic Dual In-Line (P) - 300 mil Body [PDIP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging

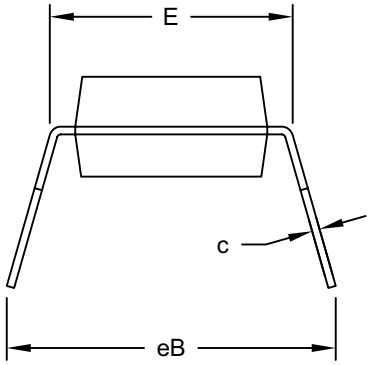


TOP VIEW





SIDE VIEW



END VIEW

Microchip Technology Drawing No. C04-018D Sheet 1 of 2